

CLAIMS

1. A communication device comprising a RFID part fixed on an insulation substrate, wherein said insulation substrate is surface-mountable on a circuit board.  
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2. A communication device comprising a RFID part fixed on a surface-mount chip antenna, wherein an antenna terminal of said RFID part is electrically connected to a terminal of said surface-mount chip antenna.  
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3. The communication device according to claim 2, wherein said surface-mount chip antenna is a coil antenna.
- 15 4. The communication device according to any one of claims 1-3, wherein fixture is achieved by resin molding.
5. The communication device according to any one of claims 2-4, wherein electrical connection is achieved by wire bonding or flip-chip mounting.  
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6. The communication device according to any one of claims 1-5, said insulation substrate or said surface-mount chip antenna having a recess, wherein said RFID part is disposed in said recess.  
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7. The communication device according to any one of claims 1-7, wherein said communication device is a communication device placed on an electronic device or other products completed through multiple process steps, said RFID part storing historical information about said process steps.  
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8. A communication device package comprising a taping

material or a bulk casing configured to package said communication device according to any one of claims 1-7.